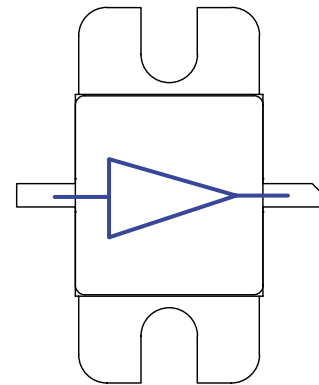


Wideband, GaN/SiC, RF Power Amplifier

0.5 - 4.0 GHz | 90 - 16 W typ | 65 - 13% Efficiency typ | 15 - 11 dB Gain typ | 100V | 150µs Pulse Width, 30% Duty Cycle

IGW4000 is a high power GaN-on-SiC RF distributed power amplifier that has been designed to suit the needs of radar and electronic warfare systems as well as general-purpose broad-band applications. It operates over the entire 0.5 - 4.0 GHz frequency range. Under 150µs, 30% Duty Cycle pulse conditions, it supplies typically >80W with 50% efficiency and 14dB gain over 0.5 - 1.5 GHz with useful performance up to 4 GHz. The amplifier is fully matched to 50Ω over the entire 0.5 - 4.0 GHz frequency range. It operates from a 100 V supply voltage. For optimal thermal efficiency, the amplifier is housed in a metal-based package with an epoxy-sealed ceramic lid.



FEATURES

- GaN on SiC HEMT Technology
- Fully matched to 50Ω at the input and output
- 100% RF Tested Under 150µs Pulse Width, 30% Duty Cycle pulse conditions
- RoHS and REACH Compliant

APPLICATIONS

- Radar and EW Systems
- General-Purpose Wideband Amplifier Applications

Table 1. Absolute Maximum Ratings (Not Simultaneous)

Parameter	Symbol	Value	Units	Test Conditions
DC Drain-Source Voltage	V_{DS}	350	V	25 °C
DC Gate-Source Voltage	V_{GS}	-8 to +1.0	V	25 °C
DC Drain Current	I_D	2	A	25 °C
DC Gate Current	I_G	1	mA	25 °C
RF Input Power	$P_{RF,IN}$	4	W	25 °C
Operating Channel Temperature	T_{CH}	-55 to +225	°C	
Storage Temperature	T_{STG}	-55 to +150	°C	
Soldering Temperature	T_{SOLDER}	260 for 60s	°C	

Note: Operation outside the limits given in this table may cause permanent damage to the Amplifier

Table 2. DC Electrical Characteristics (Case temperature = 25 °C unless otherwise stated)

Parameter	Symbol	Min	Typ	Max	Units	Test Conditions
Gate Pinch-Off Voltage	V_P	-5.0			V	$V_{DS} = 100V, I_{DS} = 1mA$
Quiescent Gate Voltage	V_Q		-2.8		V	$V_{DS} = 100V, I_{DS} = 100mA$

Table 3. RF Electrical Characteristics 100% Tested in Production (Case temperature = 30 °C unless otherwise stated)

Frequency (GHz)	Typical Pout (W)	Typical Efficiency (%)	Typical Gain (dB)	Typical IRL (dB)	Second Harmonic (dBc)	Test Conditions
0.5	94	67	15	11	-17	150µs Pulse Length, 30% Duty Cycle V _{DS} = 100V, I _{DS} = 100mA
1.0	96	50	14	14	-17	
2.0	31	21	13	16	-14	
3.0	30	21	13	12	-25	
4.0	16	13	11	13	-25	

Note: Consult Integra Technologies Application Note 001 for information on how RF output power and pulse droop are measured.

Table 4. Thermal Resistance (Tested, Case temperature = 50 °C unless otherwise stated)

Parameter	Symbol	Typ	Units	Test Conditions
Thermal Resistance, Channel to Case	R _{TH}	1.5	°C/W	Dissipated Power = 117W 150µs Pulse Length, 30% Duty Cycle V _{DS} = 100V

TYPICAL PERFORMANCE

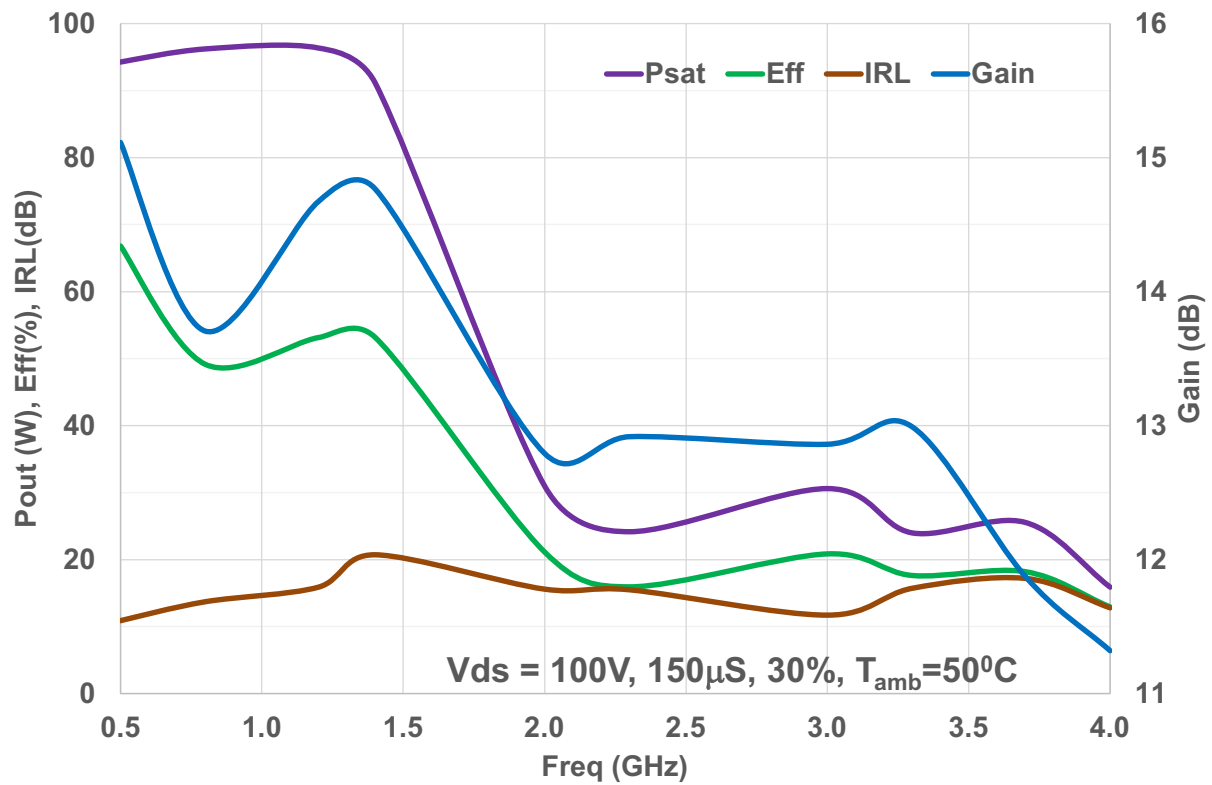
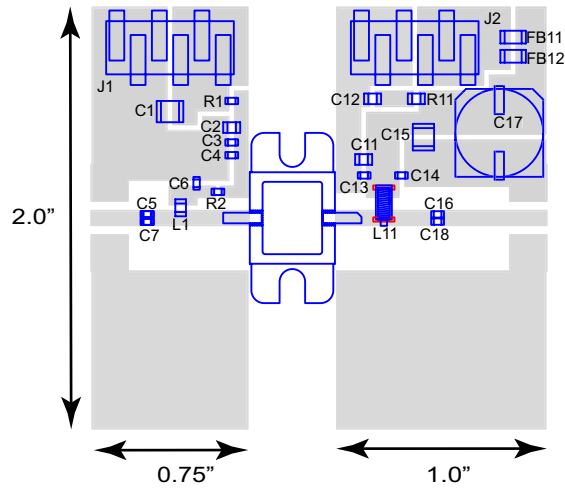


Figure 1

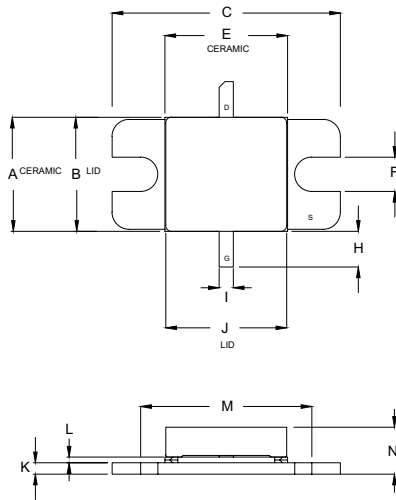
TEST FIXTURE



Bill of Materials for IGW4000 Test Fixture

Designator	Description	Quantity	Part Number
C1	CAP 4.7 μ F, 1210, 25V, X7R	1	C1210C475K3RACTU
C2	CAP 0.1 μ F, 0805, 100V, X7R	1	C2012CX7R2A104K125
C3, C4, C6, C13, C14	CAP 100pF, 250V, 0603	5	600S101FT250XT
C5, C7, C16, C18	CAP 100pF, 250V, 0603, Edge Mount	4	600S101FT250XT
C11, C12	CAP 0.068 μ F, 0805, 250V	2	C0805C683KARCAUTO
C15	CAP 0.1 μ F, 1210, 200V, X7R	1	1210CC104MAT2A
C17	CAP 33 μ F, 160V, Electrolytic	1	ULT2C330MNL1GS
L1	IND 470nH, 0805	1	CC-0805LS-471
L11	IND 105nH, 0.1 OHM, 3A	1	MK13T30.045HRS-8IC
FB11, FB12	IND FB, 33 OHM, 5A, 1206	2	BLM31PG330SN1L
R1, R2	RES, 5.11 OHM, 0603	2	MK13T30.045HRS-8IC
R11	RES, 10 OHM, 0805	1	CRCW080510R0JNEA
PC Board Type	AGC/Nelco MW4000 31mil, 1/1oz. Copper	2	

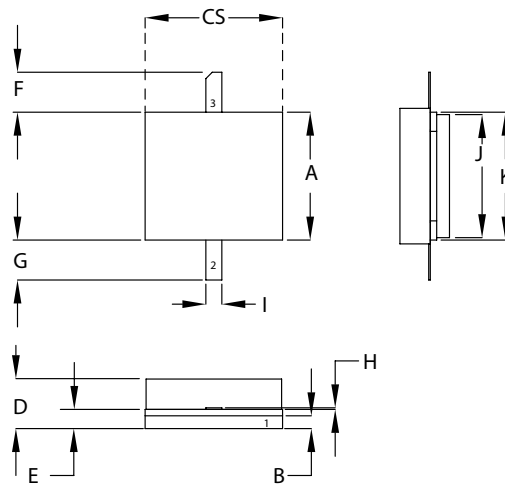
PACKAGE PL44C2CPC



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.395	0.405	10.033	10.287
B	0.396	0.404	10.059	10.261
C	0.795	0.805	20.193	20.447
E	0.425	0.435	10.795	11.049
F	0.115	0.125	2.921	3.175
H	0.110	0.140	2.794	3.556
I	0.045	0.055	1.143	1.397
J	0.420	0.428	10.668	10.871
K	0.035	0.045	0.889	1.143
L	0.018	0.022	0.457	0.559
M	0.595	0.605	15.113	15.367
N	0.125	0.157	3.175	3.987

PIN SCHEDULE	
D	DRAIN
S	SOURCE
G	GATE

IGW4000



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.395	0.405	10.03	10.28
B	0.035	0.045	0.88	1.14
CS	0.425	0.435	10.79	11.05
D	0.147	0.163	3.73	4.14
E	0.053	0.067	1.35	1.70
F	0.110	0.140	2.79	3.55
G	0.110	0.140	2.79	3.55
H	0.004	0.007	0.101	0.177
I	0.045	0.055	1.14	1.39
J	0.380	0.390	9.65	9.90
K	0.395	0.405	10.03	10.28

PIN SCHEDULE	
1	SOURCE
2	GATE
3	DRAIN

IGW4000S

ESD & MSL Rating

Parameter	Rating	Standard
ESD Human Body Model (HBM)	TBD	ESDA/JEDEC JS-001-2012
ESD Charged Device Model (CDM)	TBD	JEDEC JESD22-C101F
Moisture Sensitivity Level (MSL)	Unlimited Shelf Life	IPC/JEDEC J-STD-020

RoHS Compliance

Integra Technologies, Inc declares that its GaN and LDMOS Transistor Products comply with EU Directive 2011/65/EU on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS2), as adopted by EU member states on January 2, 2013 and amended on March 31, 2015 by EU Directive 2015/863/EU.

REACH Compliance

Integra Technologies supports EU Regulation number 1907/2006 concerning the Registration, Evaluation, Authorization, and Restriction of Chemicals (REACH) as these apply to Integra semiconductor products, development tools, and shipping packaging.

In support of the REACH regulation, Integra will:

- Inform customers and recipients of Integra product if they contain any substances that are of very high concern (SVHC) per the European Chemical Agency (ECHA) website.
- Notify ECHA if any Integra product that contains any SVHCs which exceed guidelines for REACH chemicals by weight per part number and for total content weight per year for all products produced in or imported to the European market.
- Cease shipments of product containing REACH Annex XIV substances until authorization has been obtained.
- Cease shipment of product containing REACH Annex XVII chemicals when restrictions apply.

Integra has evaluated its materials, BOMs, and product specifications and product and has determined that this transistor conforms to all REACH and SVHC regulations and guidelines. Integra has implemented actions and control programs that will assure continued compliance.

Disclaimer

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DEFINITIONS:

DATA SHEET STATUS

Advanced Specification - This data sheet contains Advanced specifications.

Preliminary Specification - This data sheet contains specifications based on preliminary measurements and data.

Final Specification - This data sheet contains final product specifications.

MAXIMUM RATINGS Stress above one or more of the maximum ratings may cause permanent damage to the device. These are maximum ratings only operation of the device at these or at any other conditions above those given in the characteristics sections of the specification is not implied. Exposure to maximum values for extended periods of time may affect device reliability.